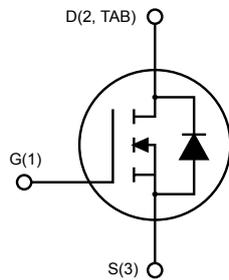
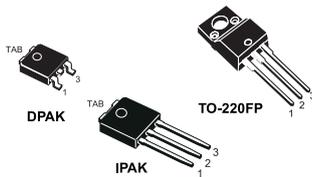


## N-channel 600 V, 0.8 $\Omega$ typ., 5 A MDmesh™ II Power MOSFETs in DPAK, TO-220FP and IPAK packages



AM01475v1\_noZen

### Features

Order code	$V_{DS}$	$R_{DS(on)}$ max.	$I_D$	Package
STD7NM60N	600 V	0.9 $\Omega$	5 A	DPAK
STF7NM60N				TO-220FP
STU7NM60N				IPAK

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

### Applications

- Switching applications

### Description

These devices are N-channel Power MOSFETs developed using the second generation of MDmesh™ technology. These revolutionary Power MOSFETs associate a vertical structure to the company's strip layout to yield one of the world's lowest on-resistance and gate charge. They are therefore suitable for the most demanding high-efficiency converters.

#### Product status link

[STD7NM60N](#)
[STF7NM60N](#)
[STU7NM60N](#)

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		DPAK, IPAK	TO-220FP	
V <sub>DS</sub>	Drain-source voltage	600		V
V <sub>GS</sub>	Gate-source voltage	±25		V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	5	5 <sup>(1)</sup>	A
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	3	3 <sup>(1)</sup>	A
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	20	20 <sup>(1)</sup>	A
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	45	20	W
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat-sink (t = 1 s, T <sub>C</sub> = 25 °C)	2.5		kV
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	15		V/ns
T <sub>J</sub>	Operating junction temperature range	-55 to 150		°C
T <sub>stg</sub>	Storage temperature range			

1. Limited by maximum junction temperature.
2. Pulse width limited by safe operating area.
3.  $I_{SD} \leq 5 \text{ A}$ ,  $di/dt \leq 100 \text{ A}/\mu\text{s}$ ,  $V_{DSpeak} \leq V_{(BR)DSS}$ ,  $V_{DD} = 80\% V_{(BR)DSS}$ .

**Table 2. Thermal data**

Symbol	Parameter	Value			Unit
		DPAK	TO-220FP	IPAK	
R <sub>thj-case</sub>	Thermal resistance junction-case	2.78	6.25	2.78	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient		62.5	100	°C/W
R <sub>thj-pcb</sub> <sup>(1)</sup>	Thermal resistance junction-pcb	50			°C/W

1. When mounted on 1inch<sup>2</sup> FR-4 board, 2 oz Cu.

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
I <sub>AS</sub> <sup>(1)</sup>	Avalanche current, repetitive or not-repetitive	2	A
E <sub>AS</sub> <sup>(2)</sup>	Single pulse avalanche energy	119	mJ

1. Pulse width limited by T<sub>J</sub> max.
2. Starting T<sub>J</sub> = 25 °C, I<sub>D</sub> = I<sub>AS</sub>, V<sub>DD</sub> = 50 V.

## 2 Electrical characteristics

( $T_{CASE} = 25\text{ °C}$  unless otherwise specified)

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$ , $V_{GS} = 0\text{ V}$	600			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$ , $V_{DS} = 600\text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$ , $V_{DS} = 600\text{ V}$ , $T_C = 125\text{ °C}$ <sup>(1)</sup>			100	$\mu\text{A}$
$I_{GSS}$	Gate body leakage current	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 20\text{ V}$			100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$ , $I_D = 2.5\text{ A}$		0.8	0.9	$\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 50\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	-	363	-	$\mu\text{F}$
$C_{oss}$	Output capacitance			24.6		
$C_{rSS}$	Reverse transfer capacitance			1.1		
$C_{oss\text{ eq.}}^{(1)}$	Equivalent capacitance time related	$V_{DS} = 0\text{ to }480\text{ V}$ , $V_{GS} = 0\text{ V}$	-	130	-	$\mu\text{F}$
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz}$ open drain	-	5.4	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 480\text{ V}$ , $I_D = 5\text{ A}$ , $V_{GS} = 0\text{ to }10\text{ V}$	-	14	-	nC
$Q_{gs}$	Gate-source charge			2.7		
$Q_{gd}$	Gate-drain charge			7.7		

1.  $C_{oss\text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300\text{ V}$ , $I_D = 2.5\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$	-	7	-	ns
$t_r$	Rise time			10		
$t_{d(off)}$	Turn-off delay time			26		
$t_f$	Fall time			12		

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current				5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		20	
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 5\text{ A}$ , $V_{GS} = 0\text{ V}$	-		1.3	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 5\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$		213		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60\text{ V}$ (see	-	1.5		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current			14		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 5\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$		265		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$ (see	-	1.8		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current			14		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics curves

Figure 1. Safe operating area for DPAK and IPAK

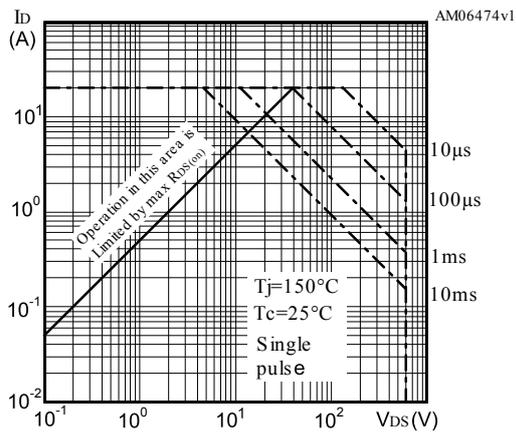


Figure 2. Thermal impedance for DPAK and IPAK

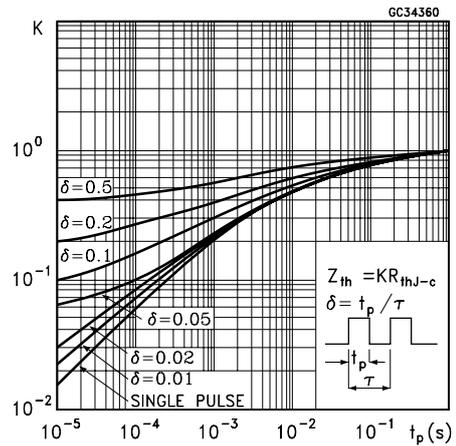


Figure 3. Safe operating area for TO-220FP

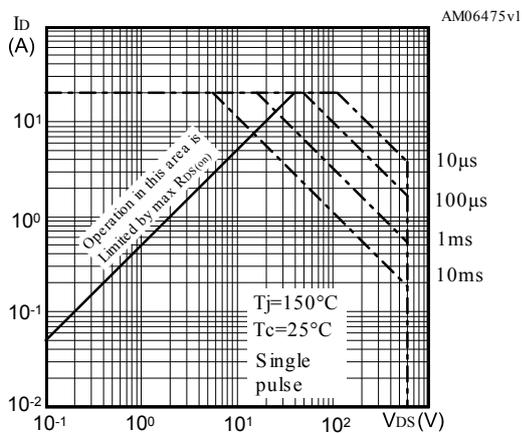


Figure 4. Thermal impedance for TO-220FP

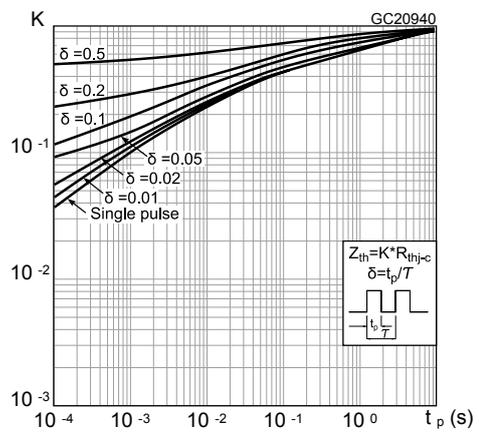


Figure 5. Output characteristics

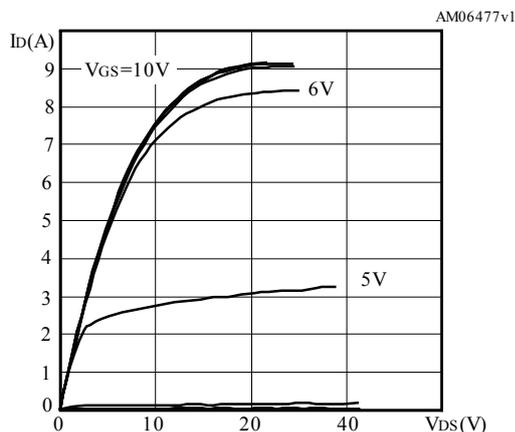
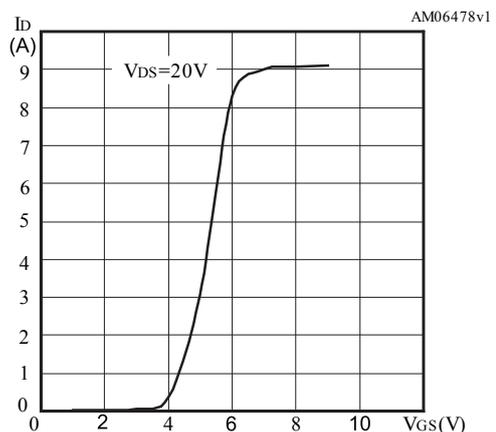


Figure 6. Transfer characteristics



## 5 Ordering information

Table 15. Order codes

Order code	Marking	Package	Packing
STD7NM60N	7NM60N	DPAK	Tape and reel
STF7NM60N		TO-220FP	Tube
STU7NM60N		IPAK	